



Material Content Data Sheet



Sales Product Name		TLE7368E		Issued		22. January 2018		
MA#		MA001314034						
Package		PG-DSO-36-51		Weight*		610.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.773	2.42	2.42	24212	24212
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		373	
	non noble metal	iron	7439-89-6	4.546	0.74		7450	
wire	non noble metal	copper	7440-50-8	184.568	30.25	31.04	302497	310413
	non noble metal	copper	7440-50-8	1.816	0.30	0.30	2976	2976
	encapsulation	organic material	carbon black	1333-86-4	0.788	0.13		1291
plastics		epoxy resin	-	36.244	5.94		59402	
	inorganic material	silicondioxide	60676-86-0	356.922	58.50	64.57	584977	645670
leadfinish	non noble metal	tin	7440-31-5	5.508	0.90	0.90	9028	9028
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1296	1296
glue	plastics	epoxy resin	-	0.977	0.16		1601	
	noble metal	silver	7440-22-4	2.931	0.48	0.64	4804	6405
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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